Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.34 EP)
Lead Count	16
Terminal Finish	100 Sn
MS Number	MS010608B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.18E-02	86.91	869100	31.88	318762
Thermosets	Epoxy & Phenol Resin	Proprietary	1.73E-03	12.78	127800	4.69	46874
Other inorganic materials	Carbon black	1333-86-4	4.20E-05	0.31	3100	0.11	1137
Subtotal			1.35 E-02	100.00	1000000	36.68	366773

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.86 E-02	96.40	963989	50.43	504284
Copper & its alloys	Iron	7439-89-6	4.83 E-04	2.50	25006	1.31	13081
Copper & its alloys	Zinc	7440-66-6	1.16 E-04	0.60	6004	0.31	3141
Copper & its alloys	Phosphorus	7723-14-0	9.65 E-05	0.50	5001	0.26	2616
Subtotal			1.93 E-02	100.00	1000000	52.31	523122

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.97 E-04	100.0	1000000	1.08	10766

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.69 E-04	100.0	1000000	1.54	15415

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.22 E-04	99.0	990000	0.87	8720
Precious metals	Palladium	7440-05-3	3.25 E-06	1.0	10000	0.01	88
Subtotal			3.25 E-04	100.0	1000000	0.88	8808

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.17 E-03	100.0	1000000	5.87	58723

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.70 E-04	77.71	777100	1.27	12739
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Butyrolactone, gamma-	96-48-0	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	1.88 E-05	3.11	31100	0.05	510
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Organosilane	TS ref# 10001	1.88 E-05	3.11	31100	0.05	510
Other inorganic materials	Copper(II) oxide	1317-38-0	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Epoxy resin modifier	TS ref# 10038	3.15 E-06	0.52	5200	0.01	85
Subtotal			6.05 E-04	100.0	1000000	1.64	16393

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.69 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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